

1 17. The power processing device according to claim 16, further including a first shielding  
2 layer disposed on an exterior surface of said multilayer printed circuit board.

1 18. The power processing device according to claim 16, further including an electrically  
2 conductive trace contained between two layers of said dielectric sheets, said conductive trace  
3 communicating with said first set of electrically conductive windings.

1 19. The power processing device according to claim 18, further including at least one  
2 component secured to an exterior surface of said multilayer printed circuit board at a location  
3 over said electrically conductive trace.

REMARKS

By this preliminary amendment, claims 16-19 have been added. No new matter is involved as the original specification, drawings, and claims fully support these claims.

Respectfully Submitted,

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Date: \_\_\_\_\_

CERTIFICATE OF MAILING (37 CFR 1.8)

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